

LEOCO CORPORATION		PRODUCTION SPECIFICATION		No.	S-11-1258-1
* 1258 SERIES CONNECTOR *					
This product specification contains the test method, the general performance and requirements for product performance of 1.25mm pitch wire to board connector series.					
1. Construction and dimensions shall be in accordance with the referenced drawings. 产品结构 and 尺寸依据所提的产品图面					
2. Characteristics 特性:					
Current rating 额定电流: 1 A AC, DC (AWG#26~30); 0.5A AC, DC (AWG#32)					
Voltage rating 额定电压: 150V AC,DC					
Temperature rating 额定温度: -25°C ~ +85°C					
Applicable wire 适用的线: conductor construction size #26 ~ #32 (Insulation O.D.1.00mm max.)					
3. Electrical performance 电气特性:					
Item 项目	Description 内容	Test Method & Condition 测试方法及条件		Requirement 要求	
3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method 103,condition A of MIL-STD-202. Test current: 10mA(DC) Open voltage: 20mV(max.)		Less than 30 mΩ.	
3-2	Insulation Resistance 绝缘电阻	It should be. tested in accordance with method 302 condition B of MIL-STD-202 When the DC 500V DC applied between adjacent contacts.		More than 500 MΩ.	
3-3	Dielectric Withstanding Voltage 耐电压	Unmated connector shall be tested in accordance with method 301 of MIL-STD-202. When the AC 500V AC (rms) for 1 minute applied between adjacent contacts.		No evidence of break-Down and flashover	
4. Mechanical Performance 机械特性 :					
Item 项目	Description 内容	Test Method & Condition 测试方法及条件		Requirement 要求	
4-1	Crimping Pull Out Force 铆合张力强度	Pulling load shall be applied between correctly crimped terminal and wire at a constant speed of : 25±3mm/minute		AWG #26: 2.0kgf min. AWG #28: 1.0kgf min. AWG #30: 0.8kgf min. AWG #32: 0.5kgf min.	
4-2	Insertion & Withdrawal Force 插入力和拔出力	Insertion and Withdrawal connectors at the speed rate of 25±3 mm/minute.		Refer to paragraph 6	
4-3	Terminal Insertion Force 插入力	Insertion the crimped terminal into the housing at the speed rate of 25±3mm per minute		0.5kgf max.	
4-4	Terminal/Housing Retention Force 保持力	The crimped terminal in a housing shall be pulled in a perpendicular at a constant speed of 25±3mm/minute.		0.5kgf min.	

LEOCO CORPORATION		PRODUCTION SPECIFICATION	No.	S-11-1258-1
4-5	Pin Retention Force Pin 针保持力	The end of a post shall be pushed in a perpendicular to base at a constant speed of 25±3mm/minute.	0.5kgf min.	
4-6	Durability 耐久性	When mated up to 50 cycles repeatedly by The rate of 10 cycles per minute.	No defects. Contact resistance shall be 60 mΩ max.	
4-7	Vibration 振动性	The connector mated PCB shall be vibrated in accordance with method 201 of MIL-STD-202 There shall be no current discontinuity longer than 1 microsecond during the test. Frequency:10~55~10 Hz/minute. Amplitude: 1.5mm P-P Period: 2 hours in each X.Y.Z.axes	No evidence of loosening of parts or electric discontinuity. Contact resistance: 60 mΩ max.	
5. Environmental Performance 环境特性 :				
Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 要求	
5-1	Humidity 耐湿性	The unmated connector shall be tested in accordance with method 103B, condition B of MIL-STD-202 Temperature:40±2°C Humidity:90-95% (RH), Period:96 hours	Appearance:No Damage	
			Contact Resistance: 60mΩ max.	
			Insulation Resistance: 50 MΩ min.	
			Dielectric Withstanding Voltage:Must meet 3-3	
5-2	Salt Spray 盐雾测试	Connector shall be tested in accordance with method 1001.1 of MIL-STD-202 Method 101D condition B. Temperature: 35±2 °C Density: 5±1 % in weight. Period: 24±4 hours.	NO damage. Contact resistance less than twice of initial.	
5-3	Solderability 可焊性	Connector termination ends shall be checked for solderability in accordance with method 208 of MIL-STD-202F. Solder temperature: 245±5 °C Immersion period: 5±0.5 sec.	NO damage. Minimum: 95 % of immersed area.	
5-4	Resistance to Soldering Heat 耐高温焊接	<u>Solder iron method:</u> Soldering Time:5±0.5 sec. Soldering Temperature:370°C~400°C <u>When reflowing:</u> Refer to paragraph 7.	NO damage	

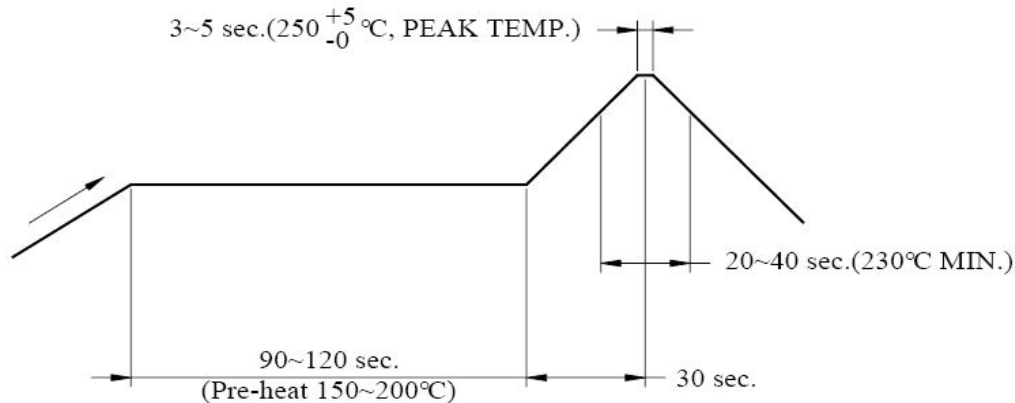
Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 标准要求
------------	-------------------	------------------------------------	---------------------

## 6. 1258 Series Insertion and Withdrawal Force:

Unit: Kgf

Number of Circuits	Insertion	Withdrawal	Number of Circuits	Insertion	Withdrawal
	(max.)	(min.)		(max.)	(min.)
Single	0.30	0.02	14	3.08	0.28
2	0.44	0.04	15	3.30	0.30
3	0.66	0.06	20	4.40	0.40
4	0.88	0.08	21	4.62	0.42
5	1.10	0.10	25	5.50	0.50
6	1.32	0.12	30	6.60	0.60
7	1.54	0.14			
8	1.76	0.16			
9	1.98	0.18			
10	2.20	0.20			
11	2.42	0.22			
12	2.64	0.24			
13	2.86	0.26			

## 7. Infrared Reflow Condition:



TEMPERATURE CONDITION GRAPH  
(TEMPERATURE ON BOARD PATTERN SIDE)

NOTE: Please check the mount condition(reflow soldering condition) by your own devices  
beforehand, because the condition changes by the soldering devices, p.c.boards, and so on.  
No moisture treatment before reflow process.

APPR BY: CHARD

CHKD BY: SMILE

SPEC BY: ANGEL